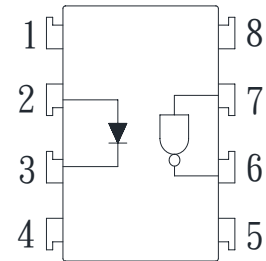


### ● Description

The KPC6N137 series consist of an LED. It is a super high-speed digital output type photocoupler packaged in a 8 pin DIP package and available in wide-lead spacing and SMD option.

### ● Schematic



- |            |                   |
|------------|-------------------|
| 1. N.C.    | 5. GND            |
| 2. Anode   | 6. Vo             |
| 3. Cathode | 7. V <sub>E</sub> |
| 4. N.C.    | 8. Vcc            |

### ● Features

1. Pb free and RoHS compliant
2. Super high-speed response (t<sub>PLH</sub>,t<sub>PHL</sub>:typ.45ns at RL=350Ω)
3. Instantaneous common mode rejection voltage(CMH:typ. 500V/us)
4. High isolation voltage between input and output (V<sub>iso</sub>:5000Vrms)
5. Low input current drive (IFHL: Max. 5mA)
6. LSTTL and TTL compatible output
7. MSL class 1
8. Agency Approvals:
  - UL Approved (No. E169586): UL1577
  - c-UL Approved (No. E169586)
  - VDE Approved (No. 40020973): DIN EN60747-5-5

### ● Applications

- High speed interfaces for computer peripherals, microcomputer systems
- High speed line receivers
- Noise reduction
- Interfaces for data transmission equipment

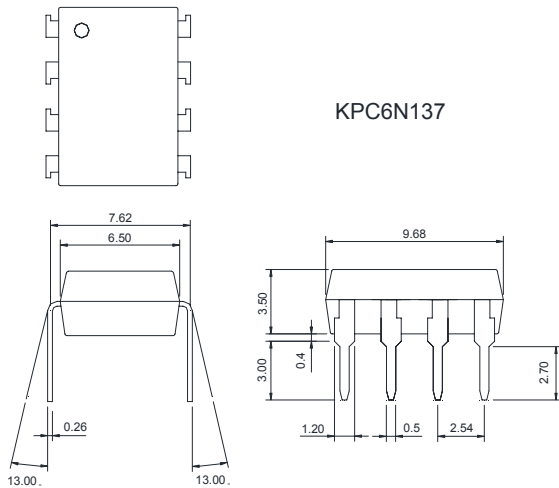
### ● Truth Table

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H
H	NC	L
L	NC	H

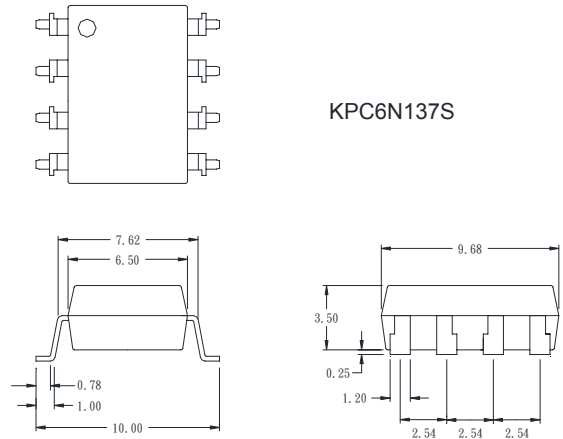
● **Outside Dimension**

Unit : mm

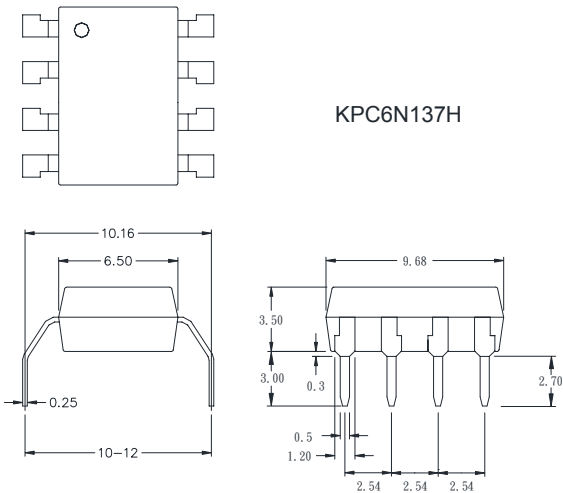
1. Dual-in-line type



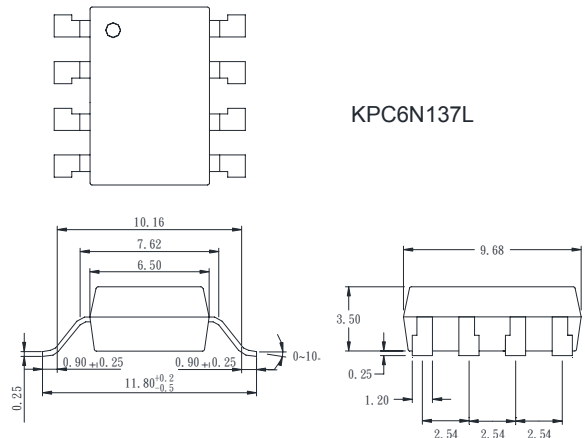
2. Surface mount type



3. Long creepage distance type

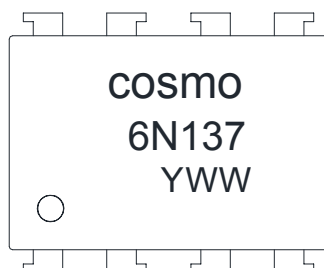


4. Long creepage distance  
for surface mount type



TOLERANCE: ±0.2mm

● **Device Marking**



**Notes:**

**COSMO**  
**6N137**  
**YWW**      Y: Year code / WW: Week code

### ● Absolute Maximum Ratings

(Ta = 25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current (*1)	$I_F$	25	mA
	Peak forward current (*2)	$I_{FM}$	40	mA
	Reverse voltage	$V_R$	5	V
	Power dissipation	$P_D$	45	mW
Output	Supply voltage	$V_{CC}$	7	V
	Enable voltage	$V_E$	5.5	V
	High level output voltage	$V_{OIL}$	7	V
	Low level output current	$I_{OL}$	50	mA
	Output collector power dissipation	$P_C$	85	mW
Isolation voltage 1 minute (*3)		Viso	5000	Vrms
Operating temperature		Topr	-40 to +85	°C
Storage temperature		Tstg	-55 to +125	°C
Soldering temperature 10 seconds		Tsol	260	°C

### ● Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
Low level input current	$I_{FL}$	0	250	µA
High level input current	$I_{FH}$	7.0	15	mA
High level enable voltage	$V_{EH}$	2.0	$V_{CC}$	V
Low level enable voltage	$V_{EL}$	0	0.8	V
Supply voltage	$V_{CC}$	4.5	5.5	V
Fanout (TTL load )	N	-	8	-

### ● Electro-optical Characteristics

(Ta = 25°C)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input forward voltage (*4)	$V_F$	$I_F=10\text{mA}, T_a=25^\circ\text{C}$	-	1.6	1.75	V
Input reverse voltage	$BV_R$	$I_R=10\mu\text{A}, T_a=25^\circ\text{C}$	5	-	-	V
Input capacitance	$C_{IN}$	$V_F=0, f=1\text{MHz}$	-	60	-	pF
Logic (1) output current	$I_{OH}$	$V_{CC}=5.5\text{V}, V_O=5.5\text{V}, I_F=250\mu\text{A}, V_E=2.0\text{V}$	-	2	250	µA
Logic (0) output voltage	$V_{OL}$	$V_{CC}=5.5\text{V}, V_{EH}=2\text{V}, I_F=5\text{mA}, I_{OL}(\text{Sinking})=13\text{mA}$	-	0.4	0.6	V
Logic (1) enable current	$I_{EH}$	$V_{CC}=5.5\text{V}, V_E=2.0\text{V}$	-	-0.8	-	mA
Logic (0) enable current	$I_{EL}$	$V_{CC}=5.5\text{V}, V_E=0.5\text{V}$	-2.0	-1.2	-	mA
Logic (1) supply current	$I_{CCH}$	$V_{CC}=5.5\text{V}, V_E=0.5\text{V}, I_F=0\text{mA}$	-	7	15	mA
Logic (0) supply current	$I_{CCL}$	$V_{CC}=5.5\text{V}, V_E=0.5\text{V}, I_F=10\text{mA}$	-	13	18	mA
Leak current (*5)	$I_{I-O}$	45%RH, $T_a=25^\circ\text{C}, t=5\text{s}, V_{I-O}=3000\text{VDC}$	-	-	1.0	mA
Isolation resistance (input-output) (*5)	$R_{I-O}$	$V_{I-O}=500\text{V}, T_a=25^\circ\text{C}$	-	$10^{12}$	-	Ω
Capacitance (input-output) (*5)	$C_{I-O}$	$f=1\text{MHz}, T_a=25^\circ\text{C}$	-	0.6	-	pF

Propagation delay time Output (0)→(1) (*7)	$t_{PLH}$	$I_F=7.5mA, V_{CC}=5V, R_L=350\Omega,$ $C_L=15pF, T_a=25^\circ C$	-	45	75	ns
Propagation delay time Output (1)→(0) (*7)	$t_{PHL}$		-	45	75	ns
Output rise-fall time (10 to 90%)	$t_{r,tf}$	$I_F=7.5mA, V_{CC}=5V, R_L=350\Omega, C_L=15pF$	-	30	-	ns
Enable propagation delay time Output (1)→(0) (*8)	$t_{ELH}$	$I_F=7.5mA, R_L=350\Omega, C_L=15pF,$ $V_{EH}=3.0V, V_{EL}=0.5V$	-	40	-	ns
Enable propagation delay time Output (0)→(1) (*8)	$t_{EHL}$		-	15	-	ns
Instantaneous common mode rejection voltage "output(0)" (*9)	$C_{MH}$	$I_F=0mA, V_{CM}=10V, V_O(\text{Min})=2.0V$ $R_L=350\Omega$	-	500	-	V/us
Instantaneous common mode rejection voltage "output(1)" (*9)	$C_{ML}$	$I_F=5mA, V_{CM}=10V, V_O(\text{Max})=0.8V$ $R_L=350\Omega$	-	-500	-	V/us

Note ) Typical values are all at  $V_{CC} = 5V, T_a = 25^\circ C$

\*1  $T_a = 0$  to  $70^\circ C$ .

\*2 Pulse width  $\leq 1ms$

\*3 40 to 80%RH AC for 1 minute,  $f=60HZ$ .

\*4 At  $I_{in} = 10mA$ ,  $V_F$  decreases at the rate of  $1.6mV/^\circ C$  if the temperature goes up. \*6  $T_a = 0$  to  $70^\circ C$ .

\*5 Measured as 2-pin element. Connect pins 2 and 3, connect pins 5, 6, 7 and 8.

\*6 DC current transfer ratio is defined as the ratio of output collector current to forward bias input current.

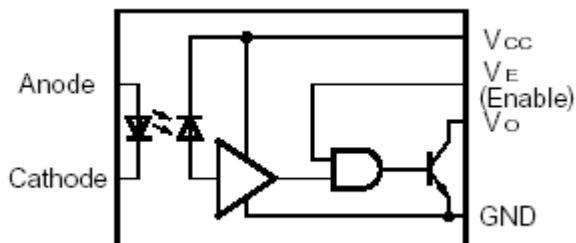
\*7 Refer to the Fig. 1.

\*8 Refer to the Fig. 2.

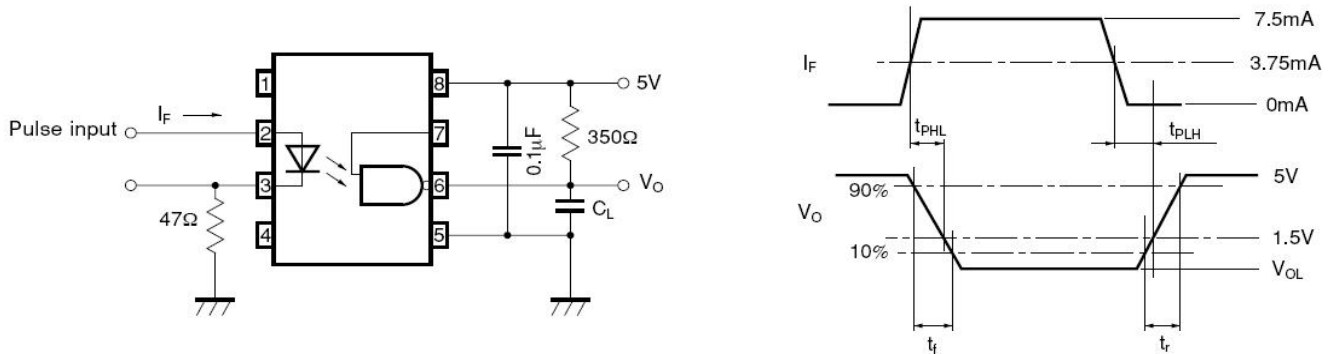
\*9  $C_{MH}$  represents a common mode voltage ignorable rise time ratio that can hold logic (1) state in output.

$C_{ML}$  represents a common mode voltage ignorable fall time ratio that can hold logic (0) state in output.

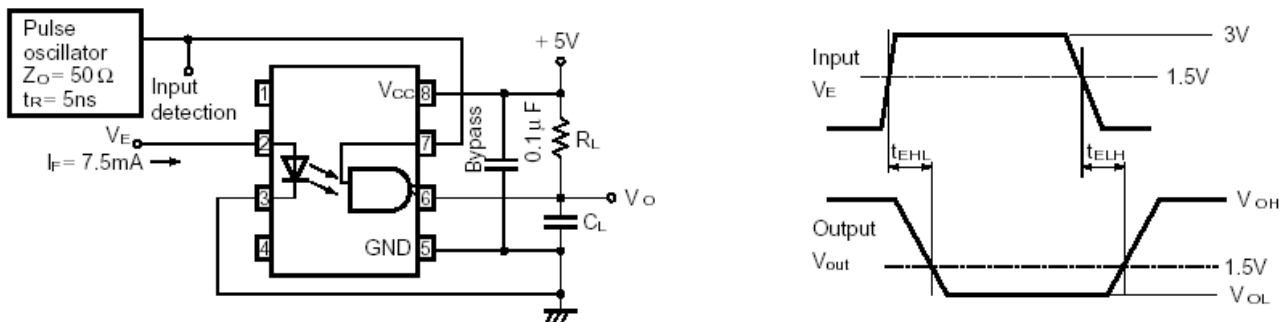
### ● Circuit Block Diagram



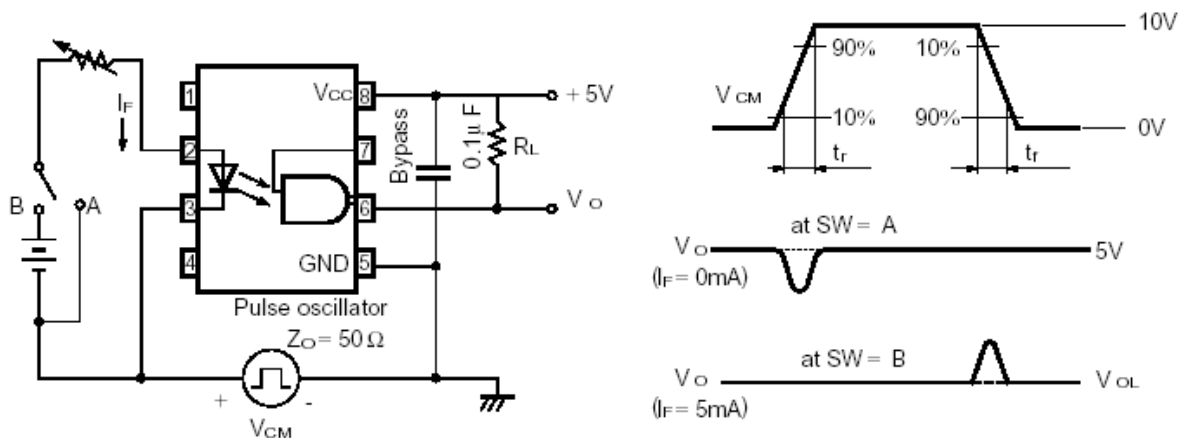
● **Test Circuit for Propagation Delay time**



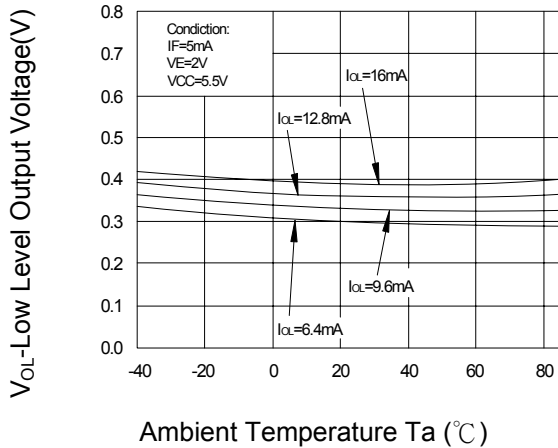
● **Test Circuit for Enable Propagation Delay Time**



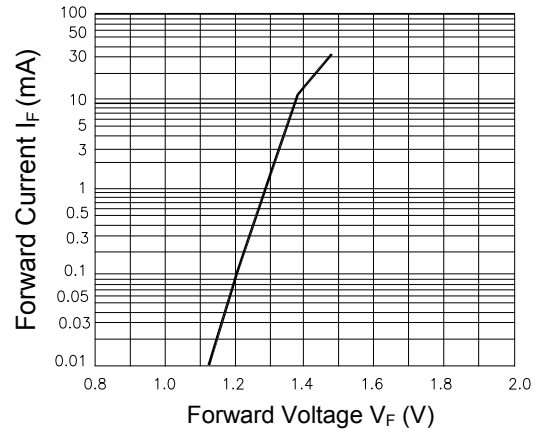
● **Test Circuit for Instantaneous Common Mode Rejection Voltage**



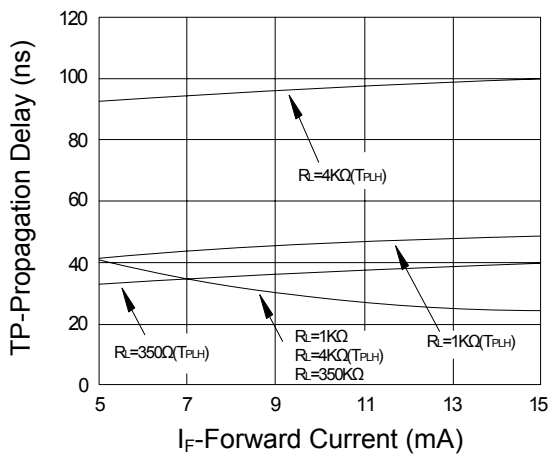
**Fig.1 Low Level Output Voltage vs. Ambient Temperature**



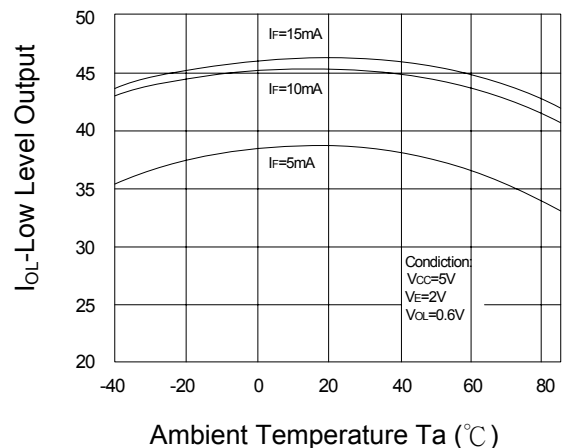
**Fig.2 Forward Current vs. Input Diode Forward Voltage**



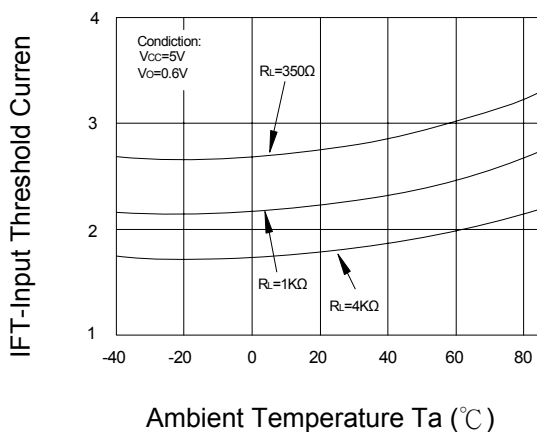
**Fig.3 Switching Time vs. Forward Current**



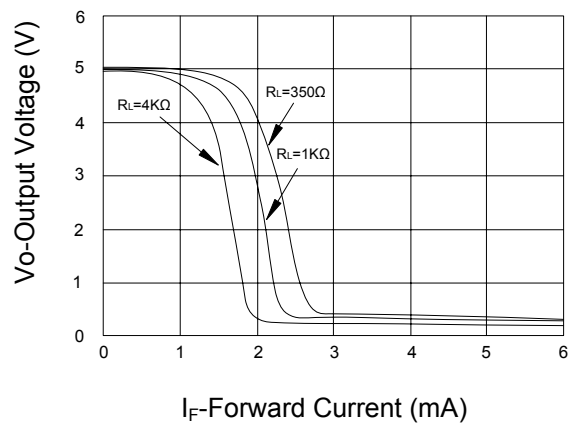
**Fig.4 Low Level Output Current vs. Ambient Temperature**



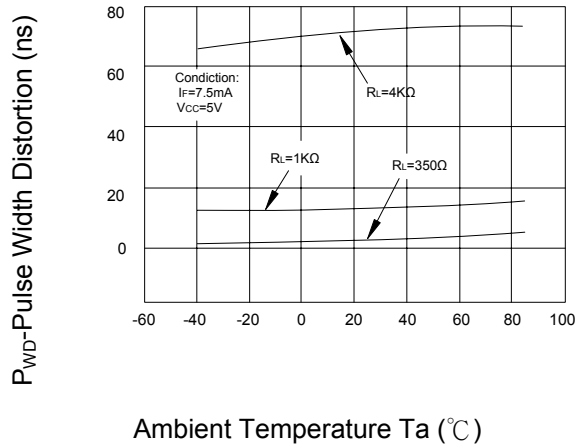
**Fig.5 Input Threshold Current vs. Ambient Temperature**



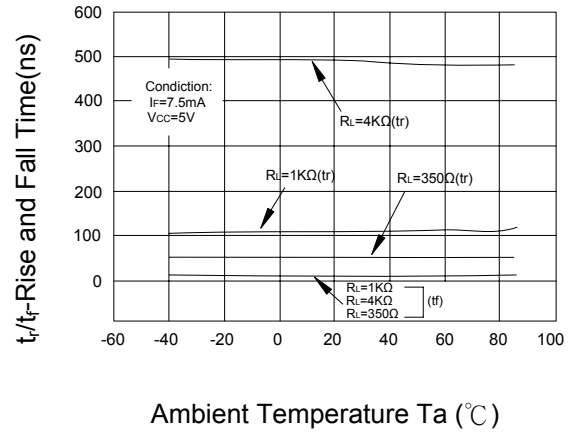
**Fig.6 Output Voltage vs. Input Forward Current**



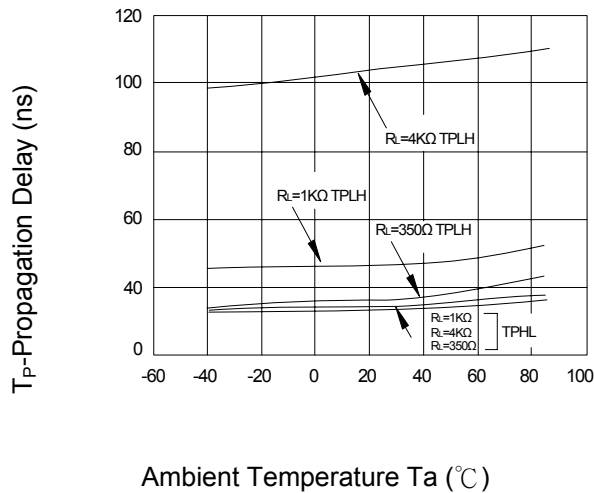
**Fig.7 Pulse Width Distortion vs. Ambient Temperature**



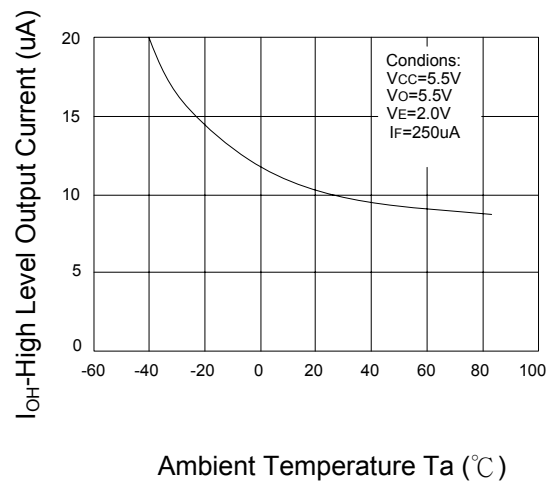
**Fig.8 Rise and Fall Time vs. Ambient Temperature**



**Fig.9 Switch Time vs. Ambient Temperature**



**Fig.10 High Level Output Current vs. Ambient Temperature**

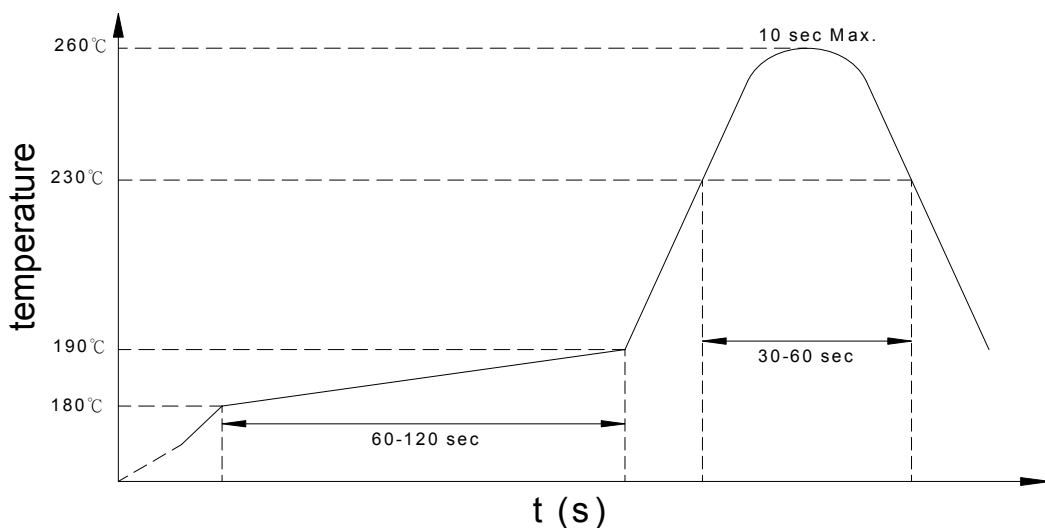


### ● Recommended Soldering Conditions

#### (a) Infrared reflow soldering :

- Peak reflow soldering : 260°C or below (package surface temperature)
- Time of peak reflow temperature : 10 sec
- Time of temperature higher than 230°C : 30-60 sec
- Time to preheat temperature from 180~190°C : 60-120 sec
- Time(s) of reflow : Two
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



#### (b) Wave soldering :

- Temperature : 260°C or below (molten solder temperature)
- Time : 10 seconds or less
- Preheating conditions : 120°C or below (package surface temperature)
- Time(s) of reflow : One
- Flux : Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (c) Cautions :

- Fluxes : Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.
- Avoid shorting between portion of frame and leads.



- **Numbering System**

## KPC6N137 X (Y)

**Notes:**

KPC6N137 = Part No.

X = Lead form option (blank · S · H · L)

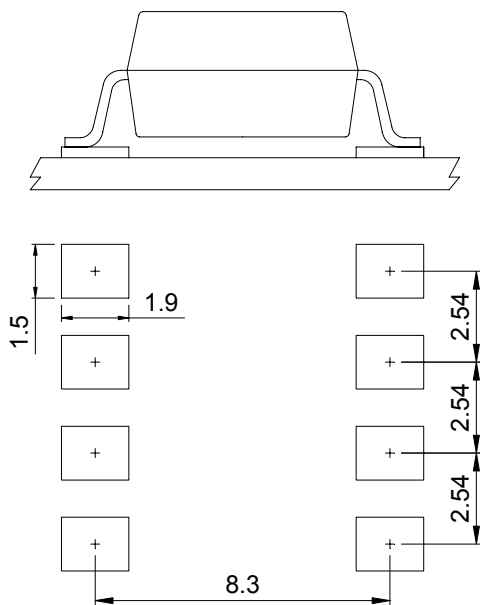
Y = Tape and reel option (TL · TR · TLD · TRU)

Option	Description	Packing quantity
S (TL)	surface mount type package + TL tape & reel option	1000 units per reel
S (TR)	surface mount type package + TR tape & reel option	1000 units per reel
L (TLD)	long creepage distance for surface mount type package + TLD tape & reel option	800 units per reel
L (TRU)	long creepage distance for surface mount type package + TRU tape & reel option	800 units per reel

- **Recommended Pad Layout for Surface Mount Lead Form**

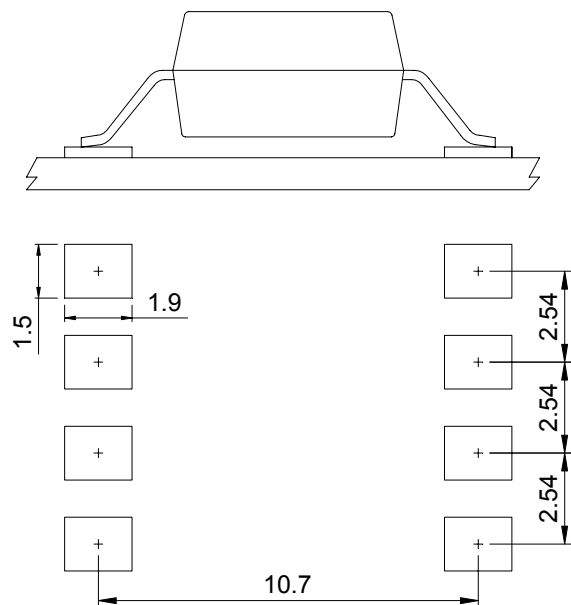
**1.Surface mount type**

8-pin SMD



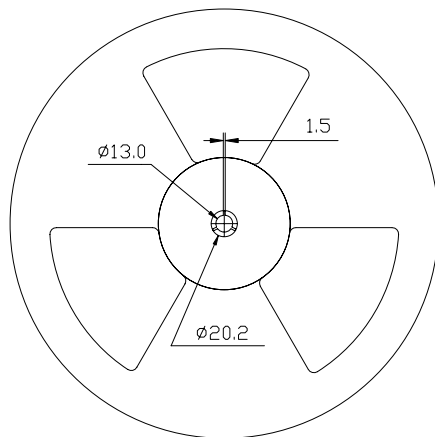
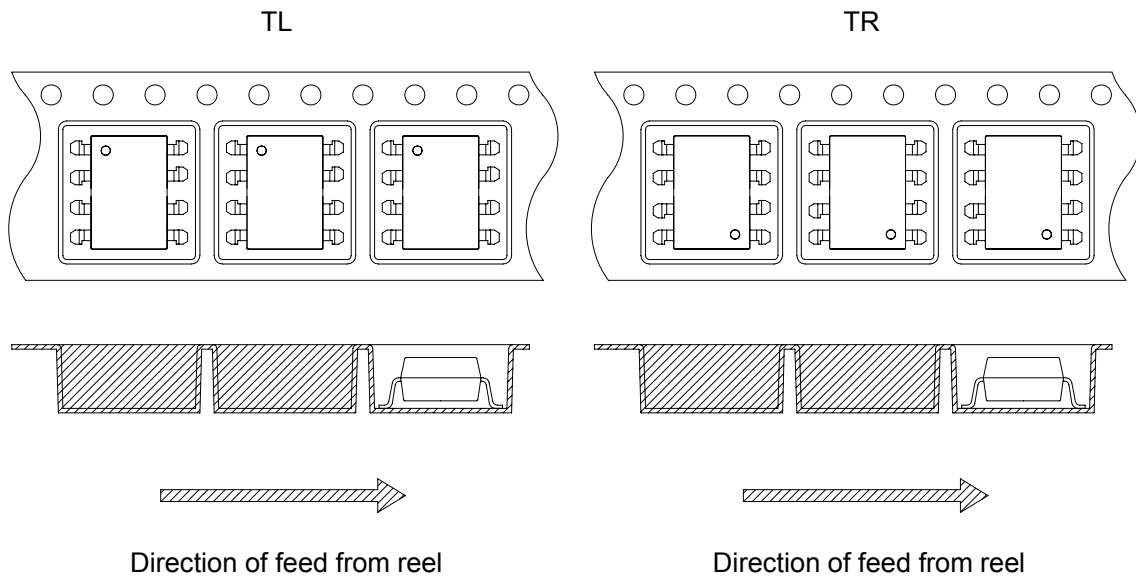
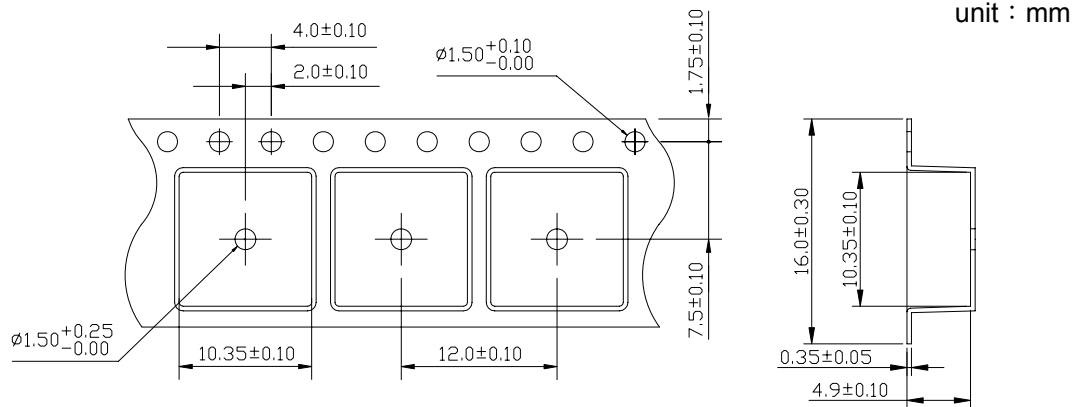
**2.Long creepage distance for surface mount type**

8-pin L

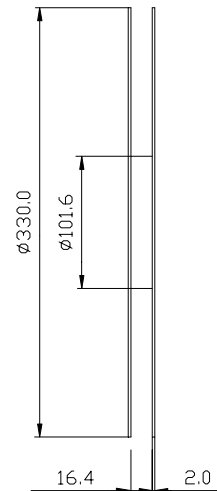


Unit :mm

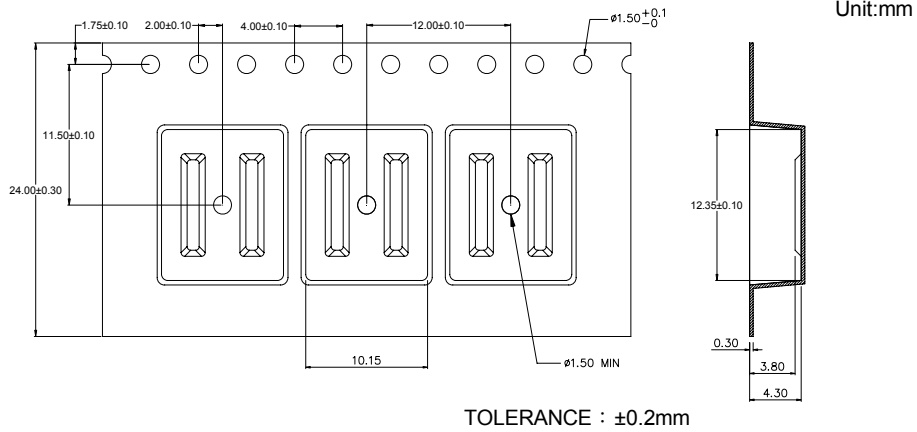
● 8-pin SMD Carrier Tape & Reel



Quantity : 1000pcs/reel

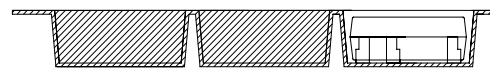
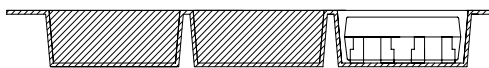
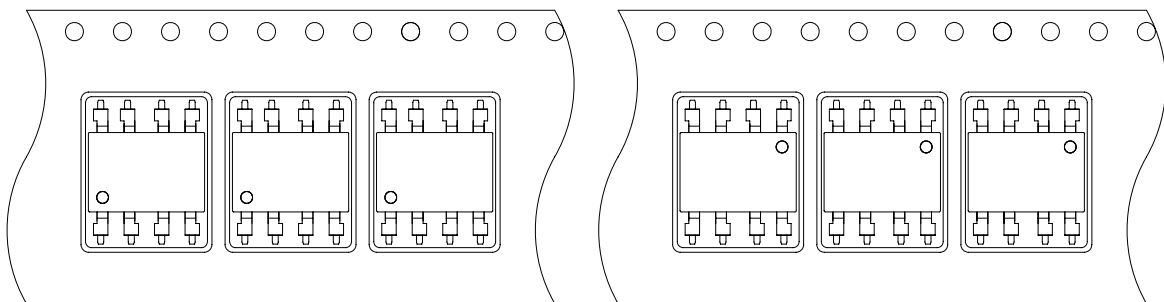


● 8-pin L Carrier Tape & Reel



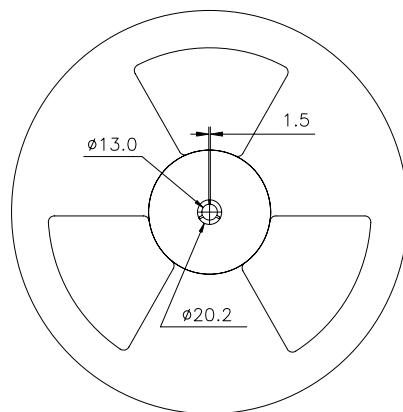
TLD

TRU

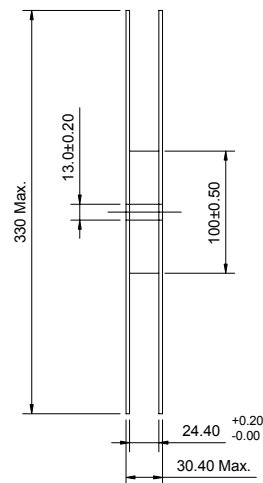


Direction of feed from reel

Direction of feed from reel



Quantity : 800pcs/reel



- **Application Notice**

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- d. Instrumentation
- e. Electrical application
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- h. Telecommunication

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